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(54) Title: TERAHERTZ IMAGER AND METHOD OF FORMING THE SAME

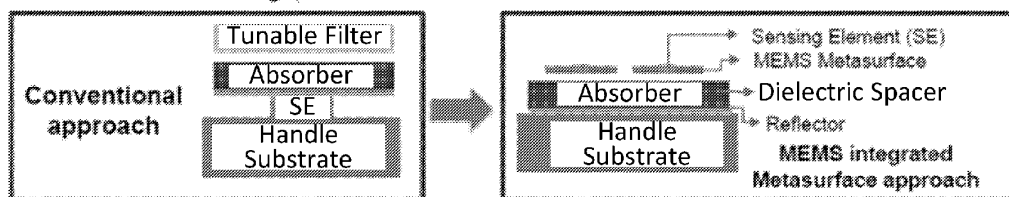


FIG. 4D

(57) Abstract: Various embodiments may relate to a terahertz (THz) imager. The terahertz imager may include a reflector layer. The terahertz imager may also include an absorber on the reflector layer. The absorber may be or may include a dielectric spacer. The terahertz imager may further include a microelectromechanical system (MEMS)-based metasurface on or over the absorber. The terahertz imager may additionally include a sensing layer.



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